KREENA DESAI

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 Mreena Desai

Education

Queen Mary University of London

September 2024 - September 2025 (Expected)

Master's of Science in Adv. Electronics and Electrical Engineering

London, UK

Pandit Deendayal Energy University

November 2020 - May 2024

Bachelor of Technology in Electronics and Communication Engineering (CGPA of 8.15/10)

Gandhinagar, Gujarat, India

Work Experience

Indian Space Research Organization (SAC, ISRO)

January 2024 - May 2024

Chip Design Intern

- Architected chip level design for Penta-Linear Array Charged Coupled Device of size 108 x 120 mm supporting space-based remote sensing and astronomical observation applications and image processing.
- Generated comprehensive Design Rule Check (DRC) and Electrical Rule Check (ERC) verification files, reducing design violations and finally generating a GDS file.
- Executed RC Extraction Analysis across 300+ signal paths, maintaining signal integrity.
- Optimized Pixel Architecture and 87um Horizontal Shift Register (HSR) layout, improving chip functionality while reducing overall power consumption.
- Implemented **Metal Routing** strategies across **8 interconnect layers**, minimizing cross-talk interference and enhancing signal quality.

Alphadecimal Networks Pvt. Ltd.

June 2023 - July 2023

Summer Intern/Trainee

- Analyzed antenna configurations and network tower architectures for **5G** deployment across multiple sites.
- Conducted 5+ on-site field assessments, documenting tower infrastructure requirements and deployment procedures.
- Studied network equipment placement and signal optimization techniques for enhanced **5G performance**.
- Evaluated network equipment deployment spanning **3 frequency bands (low, mid, high)** gaining hands-on experience with **antenna mounting**, backhaul connections and base station commissioning for large-scale 5G rollout projects

Skills

Hardware Programming Languages: MATLAB, C / C++, Assembly Language, Verilog, VHDL, JUCE

Design Softwares: Cadence Virtuoso, MATLAB/Simulink, Multisim, LTSpice, TinkerCAD

Electronic Technologies: Arduino, Chip Design, Embedded System and Microcontrollers, Semiconductor and VLSI Technologies, RF Planning, Music and Audio Programming, Analog Circuit Designing

Projects

Intelligent Sensor fusion for Hyperloop pod levitation (Continue) | MATLAB, Hardware Interfacing

- Designed integrated sensor architecture combining 4 sensors (accelerometers, proximity, magnetic field, and pressure sensors) and applied Extended Kalman Filter techniques to fuse multi-sensor data streams.
- Engineered fault-tolerant control system maintaining operational stability despite component failures or environmental interference along with a real-time control framework using fused sensor inputs to regulate ±0.1mm levitation gap.
- Validated performance gains over traditional 1 sensor approach through systematic testing and comparative analysis.

Chip Design of Penta Linear Array Charge Coupled Device (CCD) | Cadence, Virtuoso, DRC checks

- Built specialized **5 array CCD** chip architecture in Cadence, designing pixel structures (**16x16um**), horizontal shift register circuits, and multi-layer metal routing for optimal functionality.
- Generated comprehensive design rule checks and electrical rule checks verification files while executing RC extraction in Virtuoso to ensure signal integrity.
- Validated chip performance through 50+ simulation cycles, meeting the reliability requirements for orbital deployment.

Vocal Transformer: Real-time Voice Character Modification | JUCE, Projucer, C++ | GitHub

- Built real-time audio plugin using JUCE framework and C++ capable of transforming vocal inputs into 6 distinct character voices (Robot, Alien, Child, Giant, Elder, Choir).
- Implemented 8-stage DSP processing chain including phase voice coder pitch shifting, formant manipulation, and 4-voice layering capabilities.
- Designed intuitive 8+ color-coded user interface with rotary sliders and implemented phase voice coder algorithms, tanh-based soft clipping, and multi-voice layering capabilities for creative audio applications.

Publication